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Tauchi et al.

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(54) **ELECTRODE COVER FOR A PLASMA PROCESSING APPARATUS**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/158-177, 182, 184; 204/286.1, 204/297.1; 205/118, 123; 200/1 R, 5 R, 52 R, 200/315, 310, 6 A, 302.1, 308, 314, 317, 200/11 R, 16 B
CPC C25D 17/10; C25D 17/12; C25D 17/14; C25D 17/06; C25D 17/08; C25D 7/12; C25D 7/10; H01L 21/283; H01H 9/02; H01H 9/0214; H01H 9/04; H01H 9/161; H01H 13/04; H01H 13/06; H01H 13/023; H01H 21/08; H01H 19/025
See application file for complete search history.

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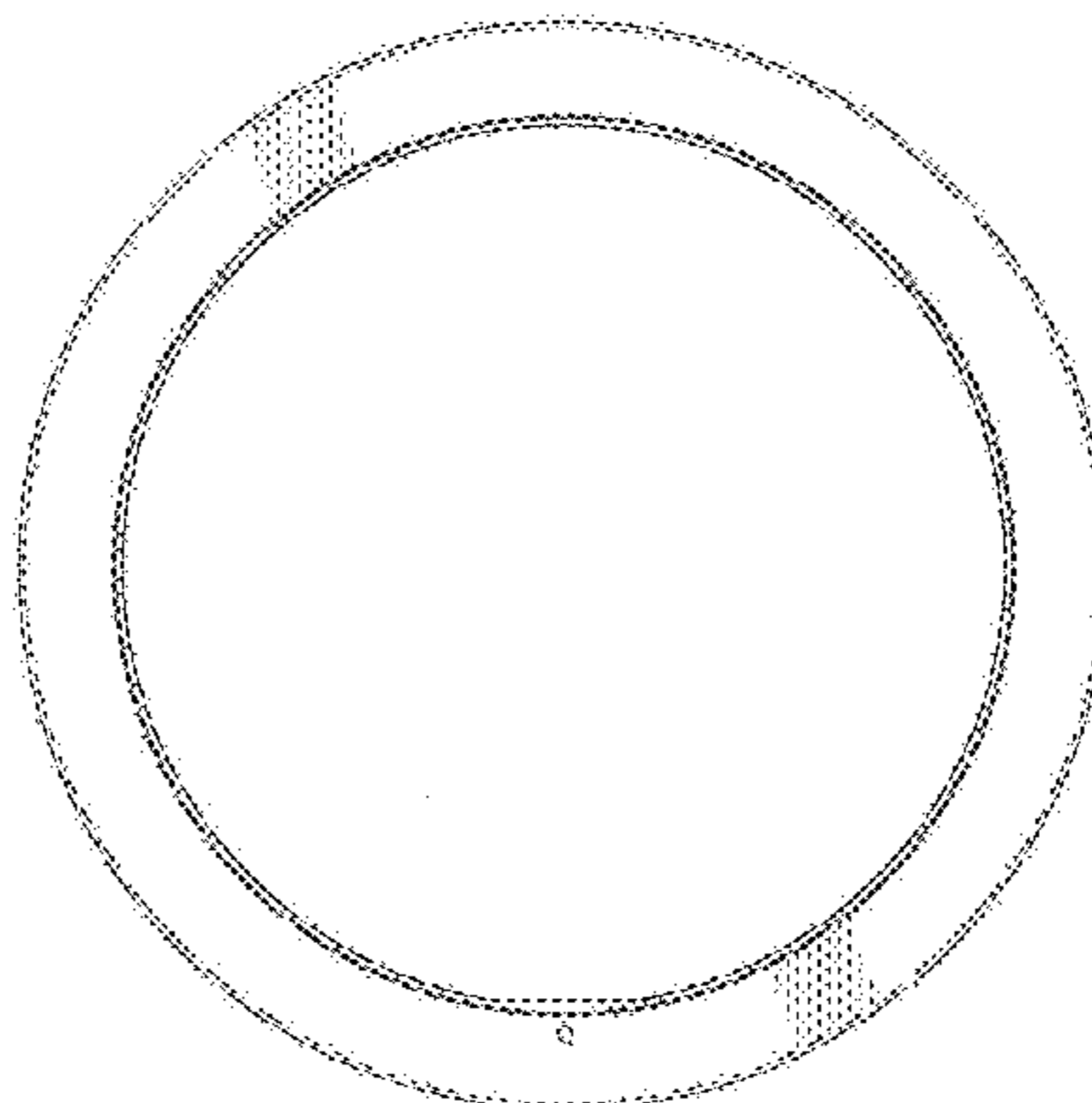
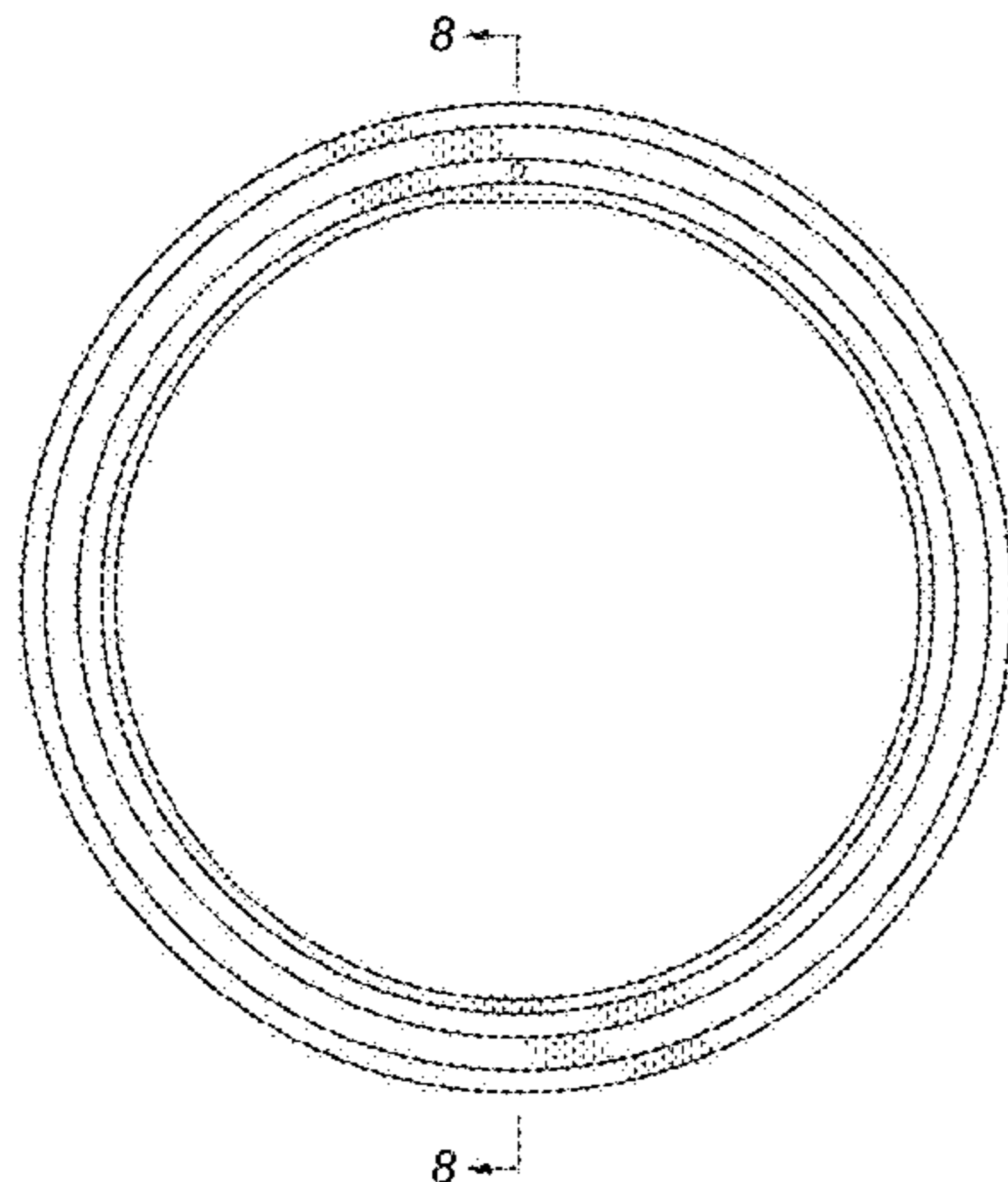
(57) **CLAIM**

The ornamental design for an electrode cover for a plasma processing apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side enlarged perspective view of an electrode cover for a plasma processing apparatus showing our new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof;
FIG. 8 is a cross-sectional view taken along line 8-8 of FIG. 6; and,
FIG. 9 is an enlarged portion view taken along line 9-9 of FIG. 8.

1 Claim, 5 Drawing Sheets



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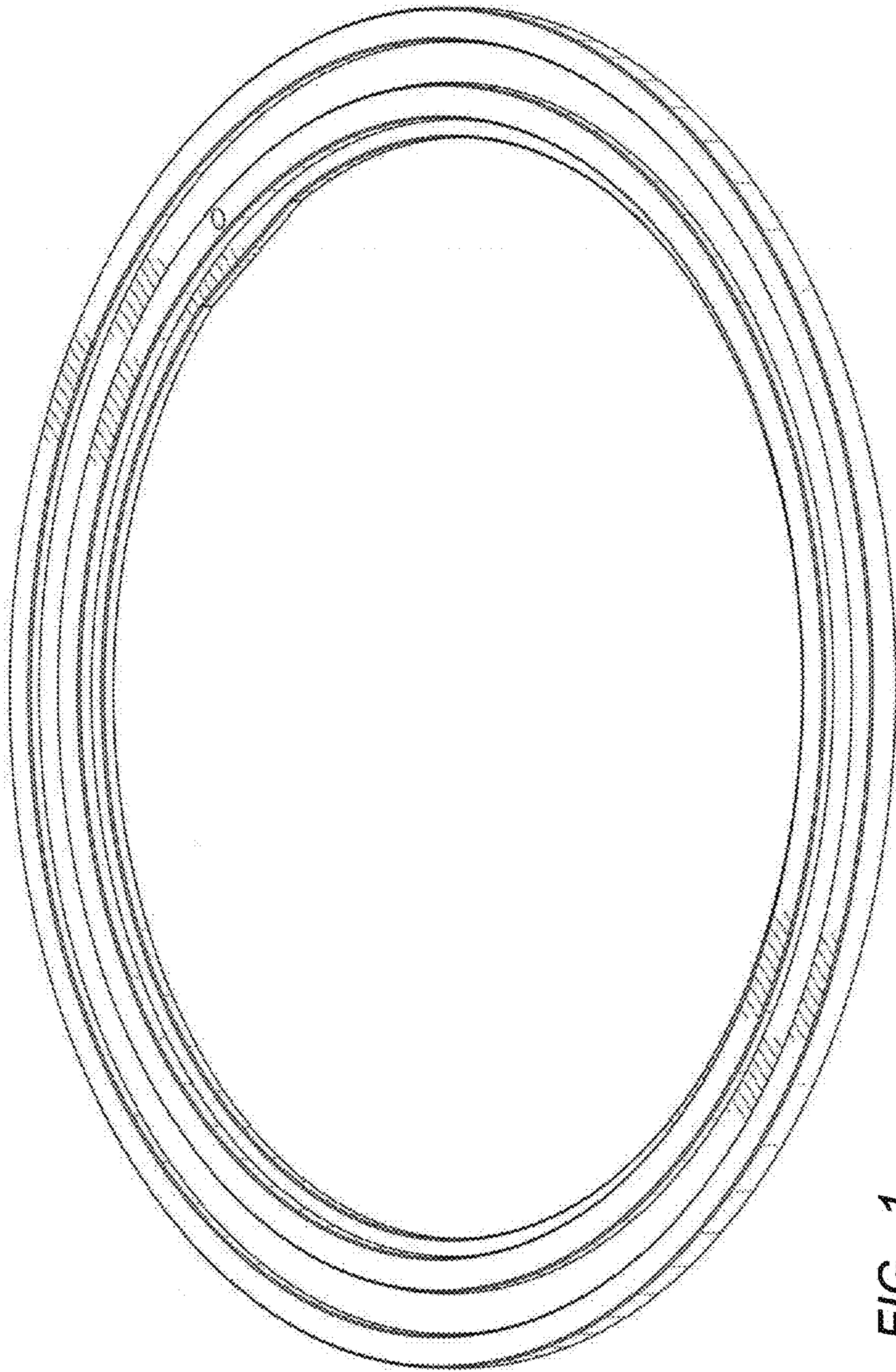


FIG. 1

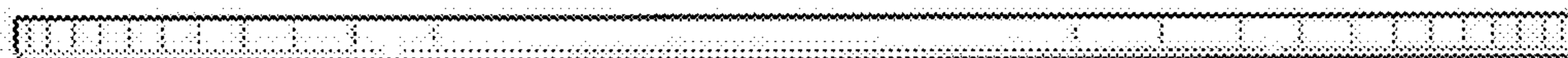


FIG. 2

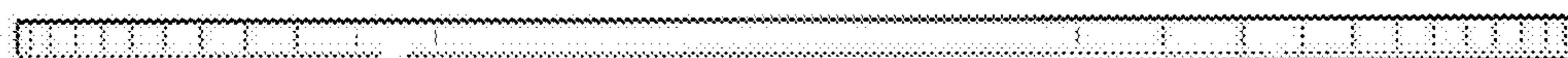


FIG. 3

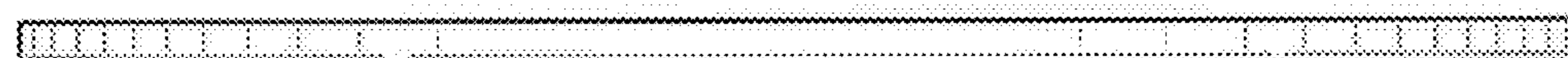


FIG. 4

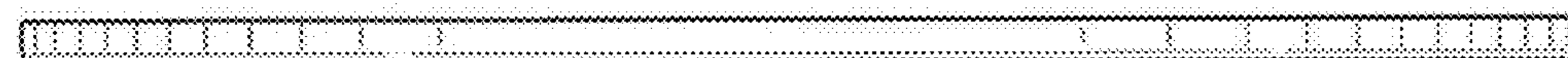


FIG. 5

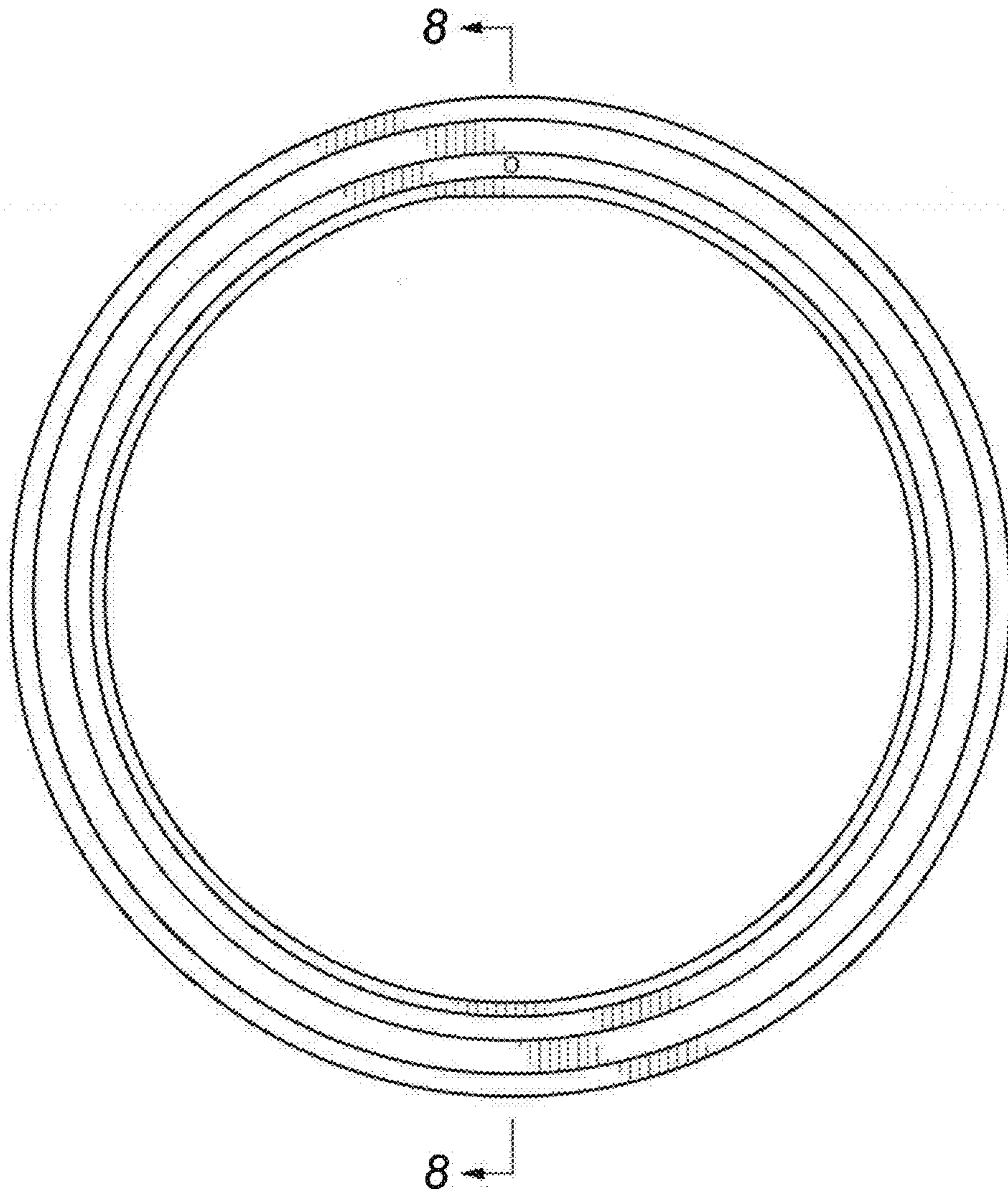


FIG. 6

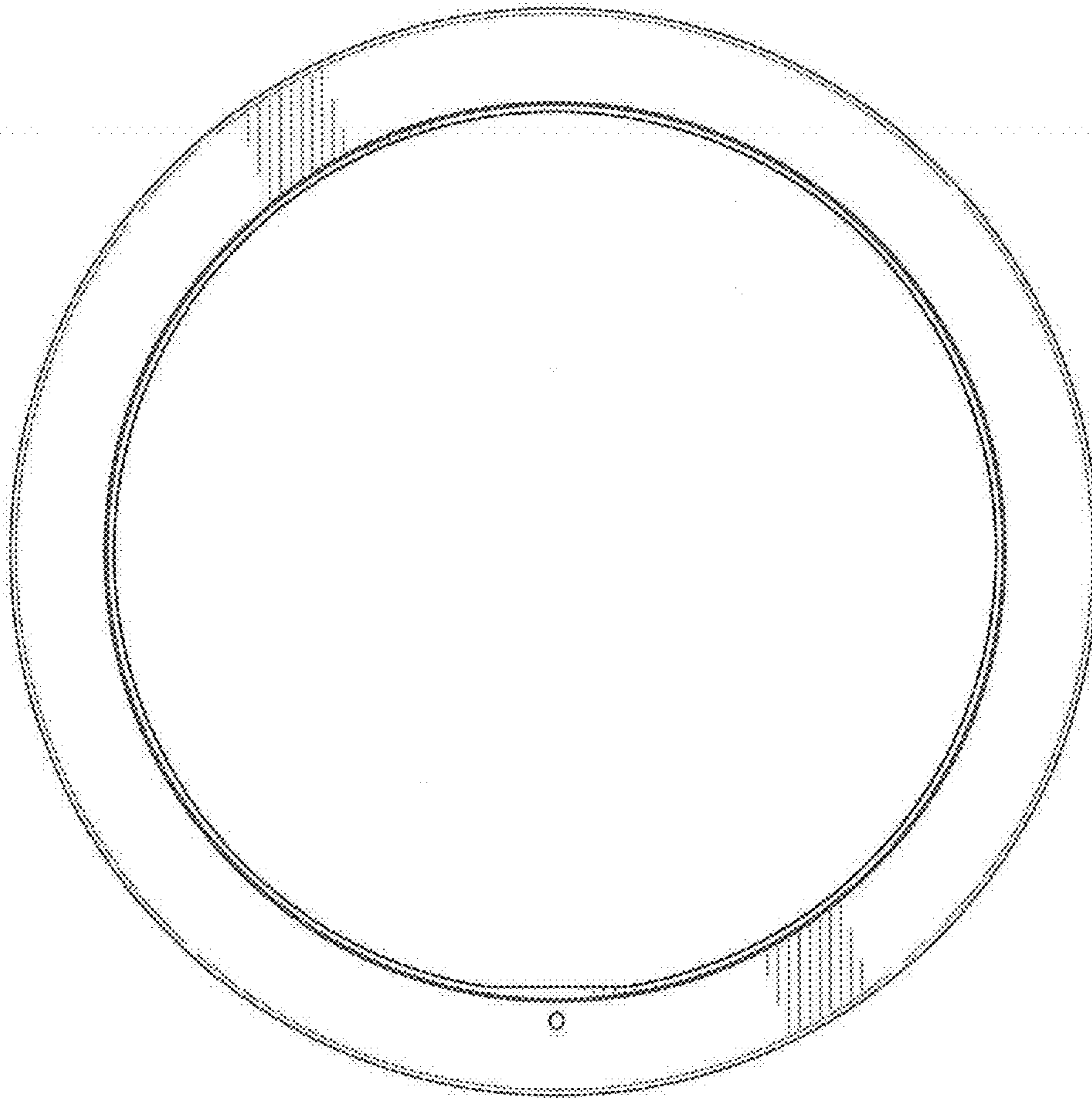


FIG. 7

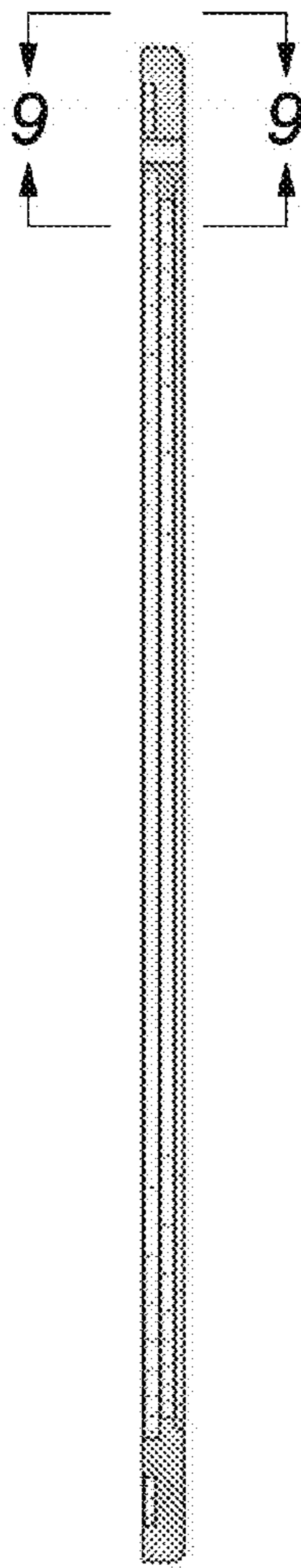


FIG. 8

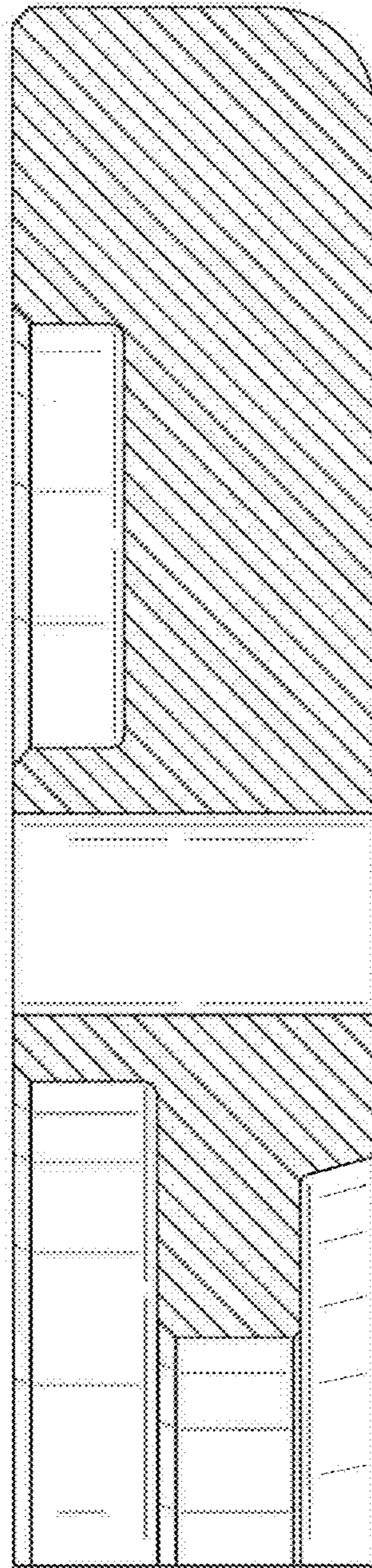


FIG. 9